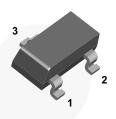
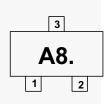
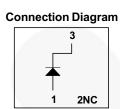
February 2015

BAS19 Small Signal Diode



SOT-23





Ordering Information

Part Number	t Number Top Mark Package		Packing Method	
BAS19	A8.	SOT-23 3L	Tape and Reel	

Absolute Maximum Ratings(1), (2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

Symbol	Parameter		Value	Unit
V _{RRM}	Maximum Repetitive Reverse Voltage		120	V
I _{F(AV)}	Average Rectified Forward Current		200	mA
I _{FSM}	Non-Repetitive Peak Forward Surge Current	Pulse Width = 1.0 second	1.0	А
		Pulse Width = 1.0 microsecond	2.0	
T _{STG}	Storage Temperature Range		-55 to +150	°C
T _J	Operating Junction Temperature		-55 to +150	°C

Notes:

- 1. These ratings are based on a maximum junction temperature of 150 $^{\circ}\text{C}.$
- 2. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

Thermal Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Value	Unit
P_{D}	Power Dissipation	350	mW
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V _R	Breakdown Voltage	I _R = 100 μA	120		V
V _F	Forward Voltage	I _F = 100 mA		1.00	V
		I _F = 200 mA		1.25	
I _R	Reverse Current	V _R = 100 V		0.1	μА
		V _R = 100 V, T _A = 150°C		100	
C _T	Total Capacitance	V _R = 0, f = 1.0 MHz		5.0	pF
t _{rr}	Reverse Recovery Time	$I_F = I_R = 30 \text{ mA}, I_{RR} = 3.0 \text{ mA}, R_L = 100 \Omega$		50	ns

Typical Performance Characteristics

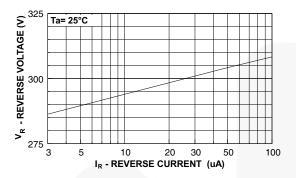


Figure 1. Reverse Voltage vs. Reverse Current BV - 1.0 to 100 μA

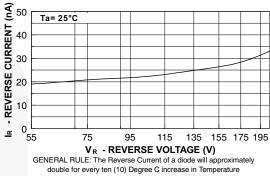


Figure 2. Reverse Current vs. Reverse Voltage

I_R - 55 to 205 V

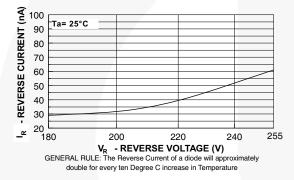


Figure 3. Reverse Current vs. Reverse Voltage I_R - 180 to 255 V

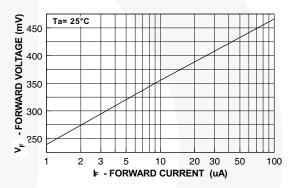


Figure 4. Forward Voltage vs. Forward Current V_F - 1.0 to 100 μ A

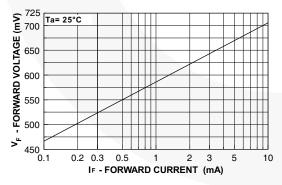


Figure 5. Forward Voltage vs. Forward Current V_F - 0.1 to 10 mA

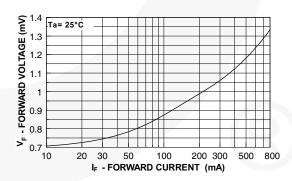


Figure 6. Forward Voltage vs. Forward Current V_F - 10 to 800 mA

Typical Performance Characteristics (Continued)

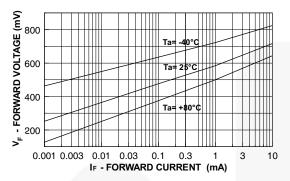


Figure 7. Forward Voltage vs. Ambient Temperature V_F - 1.0 μ A - 10 mA (- 40 to +80°C)

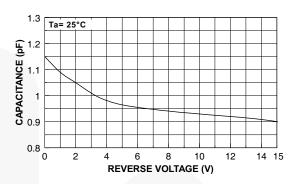


Figure 8. Capacitance vs. Reverse Voltage

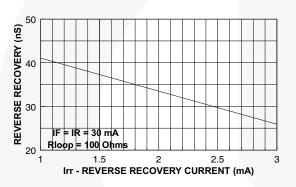


Figure 9. Reverse Recovery Time vs. Reverse Recovery Current (Irr)

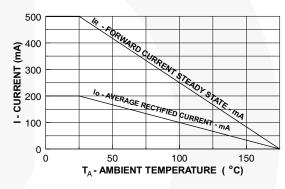


Figure 10. Average Rectified Current(I_O) and Forward Current (I_F) vs. Ambient Temperature(T_A)

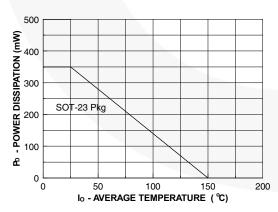


Figure 11. Power Derating Curve

Physical Dimensions 0.95 2.92±0.20 3 1.40 1.30^{+0.20}_{-0.15} 2.20 2 0.60 0.37 (0.29) -0.95 ⊕ 0.20 M A B -1.00 1.90 1.90 LAND PATTERN RECOMMENDATION SEE DETAIL A 1.20 MAX 0.10 (0.93)0.10(M) C С 2.40±0.30 NOTES: UNLESS OTHERWISE SPECIFIED **GAGE PLANE** A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H. B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.23 0.08 C) DIMENSIONS ARE INCLUSIVE OF BURRS, 0.25

MOLD FLASH AND TIE BAR EXTRUSIONS. D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994. 0.20 MIN SEATING E) DRAWING FILE NAME: MA03DREV10 **PLANE** (0.55)

DETAIL A SCALE: 2X

Figure 12. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

BitSiC™ Green FPS™
Build it Now™ Green FPS™ e-Series™

Current Transfer Logic™ Making Small Speakers Sound Louder DEUXPEED® and Better™

Dual Cool™
EcoSPARK®

EfficientMax™

ESBC™

MicroPak™

MicroPak™

MicroPak™

MicroPak™

MicroPak™

Fairchild®
Fairchild®
Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FAST®
FastvCore™
FETBench™
FPS™

MillerDrive™
MotionGrid®
MTT®
MTx®
MVN®
MVN®
mWSaver®
OptoHiT™
OPTOLOGIC®

OPTOPLANAR®

® PowerTrench® PowerXS™

Programmable Active Droop™

QFET[®]
QS[™]
Quiet Series[™]
RapidConfigure[™]

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-6
SuperSOT™-8
SuperSOT™-8
SuperSOT™-8
SuperSOT™-8
SuperSOT™-8
SuperSOT™-8
SuperSOT™-8
SuperSOT™-8

SYSTEM GENERAL®

TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™

TriFault Detect™
TRUECURRENT®*
µSerDes™

Serpes* UHC® Ultra FRFET™ UniFET™ VCX™ VisualMax™ VottagePlus™ XS™ Msens™ Misual™ UniFeT™ Misual™ Mi

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT http://www.fairchildsemi.com, FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OF CIRCUIT DESCRIBED HEREIN, NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are
 intended for surgical implant into the body or (b) support or sustain
 life, and (c) whose failure to perform when properly used in
 accordance with instructions for use provided in the labeling, can be
 reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 173

AMEYA360 Components Supply Platform

Authorized Distribution Brand:

























Website:

Welcome to visit www.ameya360.com

Contact Us:

> Address:

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

> Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com